Am386[™]DXL

High-Performance, Low-Power, 32-Bit Microprocessor

DISTINCTIVE CHARACTERISTICS

Ideal for portable PCs

- -True static design for long battery life
- -Typical standby Icc < 0.08 mA at DC
- -Typical operating lcc < 275 mA at 33 MHz
- -Lower power consumption than Intel 386DX or Intel 386SX
- -Small footprint 132-pin PQFP package*
- -Wide range of chip sets and BIOS available to support standby mode capabilities
- -Performance on demand (0 to 40 MHz)

- Ideal for desktop PCs
 - -40-, 33-, 25-, and 20-MHz operating speeds
 -Lower heat dissipation facilitates fan reduction or elimination for cost savings and size/noise reduction

Advanced Micro

Devices

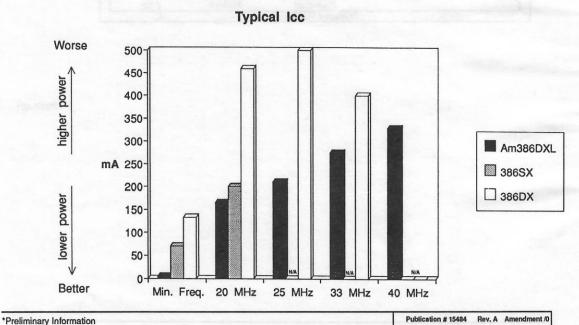
- -Pin-for-pin replacement for Intel 386DX
- Compatible with 386DX systems and software
- Supports 387DX-compatible math coprocessors
- AMD® advanced 0.8 micron CMOS technology

GENERAL DESCRIPTION

The Am386DXL microprocessor is a high-speed, true static implementation of the Intel 386DX microprocessor. It is ideal for both desktop and battery-powered portable personal computers. For desktop PCs, the Am386DXL microprocessor offers a 21% increase in the maximum operating speed from 33 to 40 MHz. Also, this device offers lower heat dissipation, allowing system designers to remove or reduce the size and cost of the system cooling fan.

For portables, the Am386DXL microprocessor's true static design offers longer battery life with low operating power consumption and standby mode. At 33 MHz, this device has 40% lower operating lcc than the Intel 386DX. Standby mode allows the Am386DXL microprocessor to be clocked down to 0 MHz (DC) and retain full register contents. In standby mode, typical current draw is less than 0.08 mA, a nearly 1000x reduction in power consumption versus the Intel 386DX or Intel 386SX.

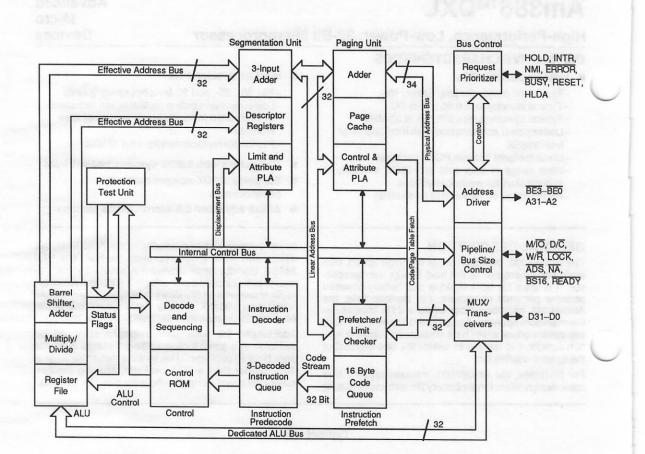
Additionally, the Am386DXL microprocessor will be available in a small footprint 132-pin plastic quad flat pack (PQFP) package*. This surface-mount package is 40% smaller than a PGA package, allowing smaller, lower-cost board designs without the need for a socket.



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BLOCK DIAGRAM



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INTRODUCTION

AMD is proud to provide the Am386DXL microprocessor at a time when the personal computer market requires alternatives. Alternate source manufacturers traditionally increase availability, add features, and broaden the market. AMD has focused significant engineering resources to bring you these benefits.

AMD's track record with the 80286 shows that we were first to raise the performance of the 80286 from 8 MHz to 10, 12, and 16 MHz. We were first to offer new packaging technology with a smaller, lower cost PLCC. Today, over 90% of all 80286s sold use PLCC packaging. AMD is committed to similar advances with the Am386DXL microprocessor.

The Am386DXL microprocessor is more than just a re-creation of the Intel 386DX. Highly skilled engineers in our Austin, Texas facility, added enhancements to the microprocessor through the use of our advanced 0.8 micron CMOS technology. These enhancements include a true static design, a low cost small footprint PQFP package, and an increase in the maximum operating speed to 40 MHz. The true static design allows for lower operating power consumption, as well as standby mode for lower heat dissipation in desktop PCs and longer battery life in portables.

AMD engineered the Am386DXL microprocessor to insure compatibility with the installed base of hardware and software for the 386-based personal computers. The Am386DXL microprocessor is your solution to meet the demand for high-performance, 32-bit desktop and portable personal computers.

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FUNCTIONAL DESCRIPTION

True Static Operation

The Am386DXL microprocessor incorporates a true static design. Unlike dynamic circuit design, the Am386DXL device eliminates the minimum operating frequency restriction. It may be clocked from its maximum speed of 40 MHz all the way down to 0 MHz (DC). System designers can use this feature to design true 32-bit battery-powered portable PCs with long battery life.

Standby Mode

This true static design allows for a standby mode. At any of its operating speeds (40 MHz to DC), the Am386DXL microprocessor will retain its state (i.e., the contents of all of its registers). By shutting off the clock completely, the device enters standby mode. Since power consumption is a function of clock frequency, operating power consumption is reduced as the frequency is lowered. In standby mode, typical current draw is reduced to less than 0.08 mA at DC.

Not only does this feature save battery life, but it also simplifies the design of power-conscious notebook computers in the following ways.

- Eliminates the need for software in BIOS to save and restore the contents of registers.
- Allows simpler circuitry to control stopping of the clock (since) the system does not need to know what state the processor is in.

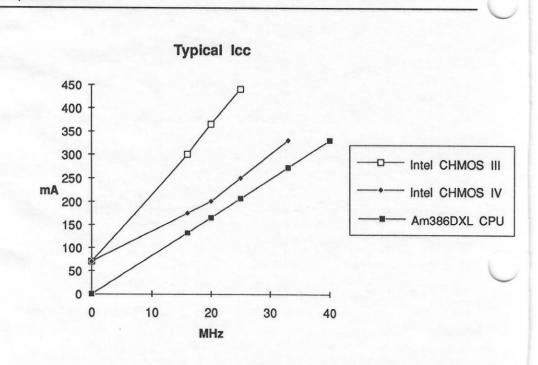
Lower Operating Icc

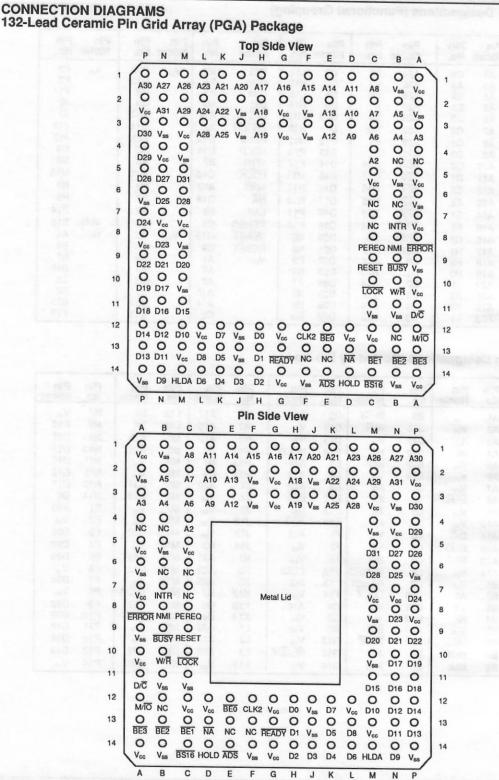
True static design also allows lower operating lcc when operating at any speed. See the following graph for typical current at operating speeds.

Performance On Demand

The Am386DXL microprocessor retains its state at any speed from 0 MHz (DC) to its maximum operating speed (20, 25, 33, or 40 MHz). With this feature, system designers may vary the operating speed of the system to extend the battery life in portable systems.

For example, the system could operate at low speeds during inactivity or polling operations. However, upon interrupt, the system clock can be increased up to its maximum speed. After a user-defined time-out period, the system can be returned to a low (or 0 MHz) operating speed without losing its state. This design maximizes battery life while achieving optimal performance.





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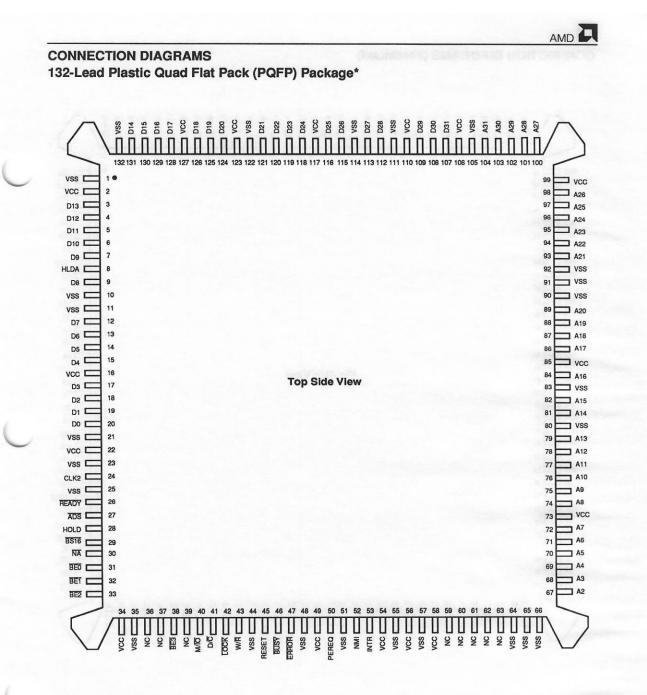
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PGA Pin Designations	(Functional Gr	ouping)
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Pin Name	Pin No.										
A2	C4	A24	L2	D6	L14	D28	M6	Vcc	C12	Vss	F2
A3	A3	A25	K3	D7	K12	D29	P4		D12		F3
A4	B3	A26	M1	D8	L13	D30	P3	~ ~	G2		F14
A5	B2	A27	N1	D9	N14	D31	M5		G3		J2
A6	C3	A28	L3	D10	M12	D/C	A11		G12		J3
A7	C2	A29	M2	D11	N13	ERROR	A8	1	G14		J12
A8	C1	A30	P1	D12	N12	HLDA	M14	19	L12		J13
A9	D3	A31	N2	D13	P13	HOLD	D14	0.0	M3		M4
A10	D2	ADS	E14	D14	P12	INTR	B7	1000	M7		M8
A11	D1	BEO	E12	D15	M11	LOCK	C10	0.0	M13		M10
A12	E3	BE1	C13	D16	N11	M/IO	A12	-	N4		N3
A13	E2	BE2	B13	D17	N10	NA	D13	1.1	N7		P6
A14	E1	BE3	A13	D18	P11	NMI	B8	1. 1.	P2		P14
A15	F1	BS16	C14	D19	P10	PEREQ	C8		P8	W/R	B10
A16	G1	BUSY	B9	D20	M9	READY	G13	Vss	A2	NC	A4
A17	H1	CLK2	F12	D21	N9	RESET	C9		AG		B4
A18	H2	DO	H12	D22	P9	Vcc	A1	0.0	A9		B6
A19	H3	D1	H13	D23	N8		A5	10	B1		B12
A20	J1	D2	H14	D24	P7		A7	0.0	B5		C6
A21	K1	D3	J14	D25	N6		A10	1.1.1.1.1	B11		C7
A22	K2	D4	K14	D26	P5		A14	0 0	B14		E13
A23	L1	D5	K13	D27	N5		C5	and and	C11		F13

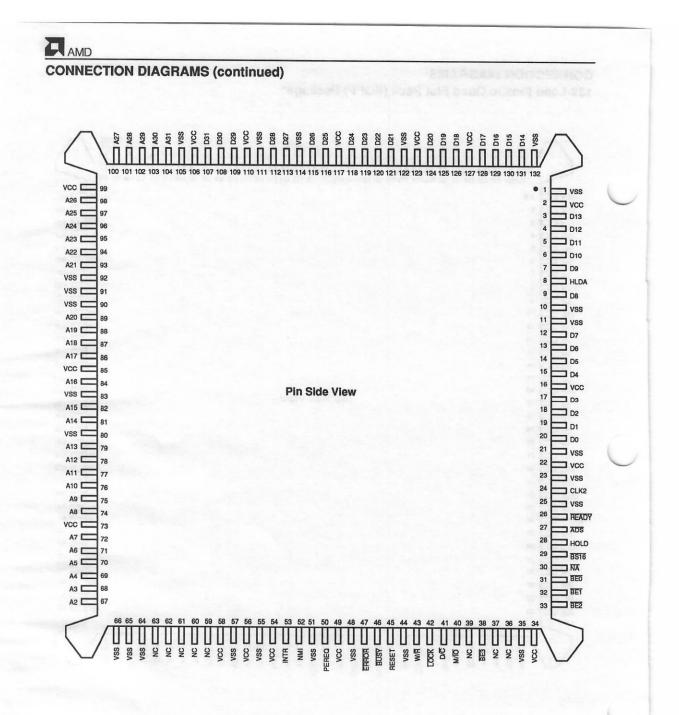
PGA Pin Designations (Sorted by Pin No.)

Pin No.	Pin Name										
A1	Vcc	B9	BUSY	D3	A9	H1	A17	L13	D8	N7	Vcc
A2	Vss	B10	W/R	D12	Vcc	H2	A18	L14	D6	N8	D23
A3	A3	B11	Vss	D13	NA	H3	A19	M1	A26	N9	D21
A4	NC	B12	NC	D14	HOLD	H12	DO	M2	A29	N10	D17
A5	Vcc	B13	BE2	E1	A14	H13	D1	M3	Vcc	N11	D16
A6	Vss	B14	Vss	E2	A13	H14	D2	M4	Vss	N12	D12
A7	Vcc	C1	A8	E3	A12	J1	A20	M5	D31	N13	D11
A8	ERROR	C2	A7	E12	BEO	J2	Vss	M6	D28	N14	D9
A9	Vss	C3	A6	E13	NC	J3	Vss	M7	Vcc	P1	A30
A10	Vcc	C4	A2	E14	ADS	J12	Vss	M8	Vss	P2	Vcc
A11	D/C	C5	Vcc	F1	A15	J13	Vss	M9	D20	P3	D30
A12	M/IO	C6	NC	F2	Vss	J14	D3	M10	Vss	P4	D29
A13	BE3	C7	NC	F3	Vss	K1	A21	M11	D15	P5	D26
A14	Vcc	C8	PEREQ	F12	CLK2	K2	A22	M12	D10	P6	Vss
B1	Vss	C9	RESET	F13	NC	K3	A25	M13	Vcc	P7	D24
B2	A5	C10	LOCK	F14	Vss	K12	D7	M14	HLDA	P8	Vcc
B3	A4	C11	Vss	G1	A16	K13	D5	N1	A27	P9	D22
B4	NC	C12	Vcc	G2	Vcc	K14	D4	N2	A31	P10	D19
B5	Vss	C13	BE1	G3	Vcc	L1	A23	N3	Vss	P11	D18
B6	NC	C14	BS16	G12	Vcc	L2	A24	N4	Vcc	P12	D14
B7	INTR	D1	A11	G13	READY	L3	A28	N5	D27	P13	D13
B8	NMI	D2	A10	G14	Vcc	L12	Vcc	N6	D25	P14	Vss



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Note: Pin 1 is marked for orientation.

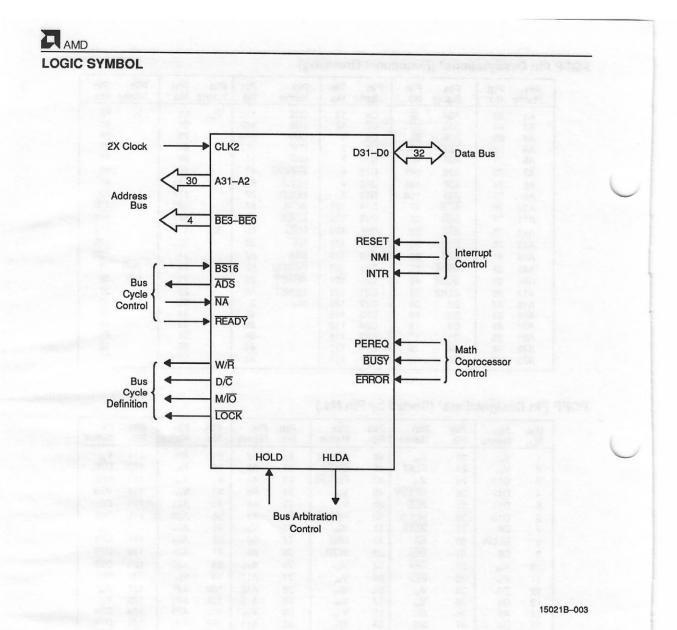
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Pin Name	Pin No.										
A2	67	A24	96	D6	13	D28	112	Vcc	56	Vss	64
A3	68	A25	97	D7	12	D29	109		58		65
A4	69	A26	98	D8	9	D30	108		73		66
A5	70	A27	100	D9	7	D31	107	1000	85	19003	80
A6	71	A28	101	D10	6	D/C	41		99		83
A7	72	A29	102	D11	5	ERROR	47		106		90
A8	74	A30	103	D12	4	HLDA	8	122	110		91
A9	75	A31	104	D13	3	HOLD	28		117		92
A10	76	ADS	27	D14	131	INTR	53		123	Bell	105
A11	77	BEO	31	D15	130	LOCK	42	150000	127		111
A12	78	BE1	32	D16	129	M/IO	40	Vss	1		114
A13	79	BE2	33	D17	128	NA	30		10		122
A14	81	BE3	38	D18	126	NMI	52		11		132
A15	82	BS16	29	D19	125	PEREQ	50	1235	21	W/R	43
A16	84	BUSY	46	D20	124	READY	26		23	NC	36
A17	86	CLK2	24	D21	121	RESET	45		25		37
A18	87	DO	20	D22	120	Vcc	2	1111	35		39
A19	88	D1	19	D23	119		16		44		59
A20	89	D2	18	D24	118		22	1.1.1.1	48		60
A21	93	D3	17	D25	116		34		51	1	61
A22	94	D4	15	D26	115		49		55		62
A23	95	D5	14	D27	113		54		57		63

PQFP Pin Designations* (Functional Grouping)

PQFP Pin Designations* (Sorted by Pin No.)

Pin No.	Pin Name										
1	Vss	23	Vss	45	RESET	67	A2	89	A20	111	Vss
2	Vcc	24	CLK2	46	BUSY	68	A3	90	Vss	112	D28
3	D13	25	Vss	47	ERROR	69	A4	91	Vss	113	D27
4	D12	26	READY	48	Vss	70	A5	92	Vss	114	VSS
5	D11	27	ADS	49	Vcc	71	A6	93	A21	115	D26
6	D10	28	HOLD	50	PEREQ	72	A7	94	A22	116	D25
7	D9	29	BS16	51	Vss	73	Vcc	95	A23	117	Vcc
8	HLDA	30	NA	52	NMI	74	A8	96	A24	118	D24
9	D8	31	BEO	53	INTR	75	A9	97	A25	119	D23
10	Vss	32	BE1	54	Vcc	76	A10	98	A26	120	D22
11	Vss	33	BE2	55	Vss	77	A11	99	Vcc	121	D21
12	D7	34	Vcc	56	Vcc	78	A12	100	A27	122	Vss
13	D6	35	Vss	57	Vss	79	A13	101	A28	123	Vcc
14	A5	36	NC	58	Vcc	80	Vss	102	A29	124	D20
15	D4	37	NC	59	NC	81	A14	103	A30	125	D19
16	Vcc	38	BE3	60	NC	82	A15	104	A31	126	D18
17	D3	39	NC	61	NC	83	Vss	105	Vss	127	Vcc
18	D2	40	M/IO	62	NC	84	A16	106	Vcc	128	D17
19	D1	41	D/C	63	NC	85	Vcc	107	D31	129	D16
20	DO	42	LOCK	64	Vss	86	A17	108	D30	130	D15
21	Vss	43	W/R	65	Vss	87	A18	109	D29	131	D14
22	Vcc	44	Vss	66	Vss	88	A19	110	Vcc	132	Vss

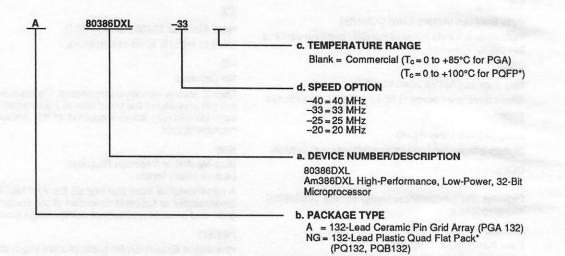


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ORDERING INFORMATION

Standard Products

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of: a. Device Number/Description b. Package Type c. Temperature Range d. Speed Option



	Valid Combinatio	ons
A	80386DXL	-40 -33 -25 -20

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. All speeds may not be available in all package combinations. Consult the local AMD sales office to confirm weitbelite of each list with a set between the set of th availability of specific valid combinations and to check on newly released combinations.

*Preliminary Information.

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PIN DESCRIPTION

A31-A2

Address Bus (Outputs)

Outputs physical memory or port I/O addresses.

ADS

Address Status (Active Low; Output)

Indicates that a valid bus cycle definition and address $(W/\overline{R}, D/\overline{C}, M/\overline{IO}, \overline{BE0}, \overline{BE1}, \overline{BE2}, \overline{BE3}, and A31-A2)$ are being driven at the Am386DXL microprocessor pins.

BE3-BE0

Byte Enables (Active Low; Outputs)

Indicate which data bytes of the data bus take part in a bus cycle.

BS16

Bus Size 16 (Active Low; Input)

Allows direct connection of 32-bit and 16-bit data buses.

BUSY

Busy (Active Low; Input)

Signals a busy condition from a processor extension.

CLK2

Clock (Input)

Provides the fundamental timing for the Am386DXL microprocessor.

D31-D0

Data Bus (Inputs/Outputs)

Inputs data during memory, I/O, and interrupt acknowledge read cycles; and outputs data during memory and I/O write cycles.

D/C

Data/Control (Output)

A bus cycle definition pin that distinguishes data cycles, either memory or I/O, from control cycles which are: interrupt acknowledge, halt, and instruction fetching.

ERROR

Error (Active Low; Input)

Signals an error condition from a processor extension.

HLDA

Bus Hold Acknowledge (Active High; Output)

Indicates that the Am386DXL microprocessor surrendered control of its local bus to another bus master.

HOLD

Bus Hold Request (Active High; Input)

Allows another bus master to request control of the local bus.

INTR

Interrupt Request (Active High; Input)

A maskable input that signals the Am386DXL microprocessor to suspend execution of the current program and execute an interrupt acknowledge function.

LOCK

Bus Lock (Active Low; Output)

A bus cycle definition pin that indicates that other system bus masters are denied access to the system bus while it is active.

M/IO

Memory I/O (Output)

A bus cycle definition pin that distinguishes memory cycles from input/output cycles.

NA

Next Address (Active Low; Input)

Used to request address pipelining.

NC

No Connect

Should always remain unconnected. Connection of a NC pin may cause the processor to malfunction or be incompatible with future steppings of the Am386DXL microprocessor.

NMI

Non-Maskable Interrupt Request (Active High; Input)

A non-maskable input that signals the Am386DXL microprocessor to suspend execution of the current program and execute an interrupt acknowledge function.

PEREQ

Processor Extension Request (Active High; Input)

Indicates that the processor extension has data to be transferred by the Am386DXL microprocessor.

READY

Bus Ready (Active Low; Input) Terminates the bus cycle.

RESET

Reset (Active High; Input)

Suspends any operation in progress and places the Am386DXL microprocessor in a known reset state.

Vcc

System Power (Active High; Input) Provides the +5 V nominal DC supply input.

Vss

System Ground (Input)

System ground provides 0 V connection from which all inputs and outputs are measured.

W/R Write/Read (Output)

A bus cycle definition pin that distinguishes write cycles from read cycles.



ABSOLUTE MAXIMUM RATINGS

Storage Temperature -65°C to +150°C Case Temperature Under Bias -65°C to +110°C Supply Voltage with Respect to Vss -0.5 V to +6.5 V

Voltage on Other Pins -0.5 V to Vcc +0.5 V

Stresses above those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

DC CHARACTERISTICS over COMMERCIAL operating ranges

 $V_{CC} = 5 V \pm 5\%$; $T_{CASE} = 0^{\circ}C$ to +85°C (PGA) $V_{CC} = 5 V \pm 10\%$; $T_{CASE} = 0^{\circ}C$ to +100°C (PQFP*)

Symbol	Parameter Description	Notes	Min	Max	Unit
ViL	Input Low Voltage	(Note 1)	-0.3	0.8	V
VIH	Input High Voltage	and the second s	2.0	V _{cc} +0.3	V
VILC	CLK2 Input Low Voltage	(Note 1)	-0.3	0.8	V
Vihc	CLK2 Input High Voltage 20 MHz 25, 33, and 40 MHz	a crianar Barris S	V _{cc} -0.8 3.7	V _{cc} + 0.3 V _{cc} + 0.3	v v
V _{ol}	Output Low Voltage I _{oL} = 4 mA: A31–A2, D31–D0 I _{oL} = 5 mA: BE3–BE0, W/R, D/C, M/IO, LOCK, ADS, HLDA			0.45 0.45	v v
V _{он}	Output High Voltage I _{он} = 1 mA: A31–A2, D31–D0 I _{он} = 0.9 mA: <u>ВЕ3–ВЕ0,</u> W/R, D/C, M/IO, LOCK, ADS, HLDA		2.4 2.4		v v
lu	Input Leakage Current (All pins except BS16, PEREQ, BUSY, and ERROR)	$0 V \le V_{IN} \le V_{CC}$		±15	μΑ
In	Input Leakage Current (PEREQ Pin)	V _{iH} = 2.4 V (Note 2)		200	μΑ
lı.	Input Leakage Current (BS16, BUSY, and ERROR)	V _{IL} = 0.45 (Note 3)		-400	μA
luo	Output Leakage Current	$0.45 V \le V_{OUT} \le V_{CC}$		±15	μΑ
lcc	Supply Current CLK2 = 40 MHz: with -20 CLK2 = 50 MHz: with -25	(Note 4) I _{cc} Typ = 165 I _{cc} Typ = 210		200 250	mA mA
	CLK2 = 66 MHz: with -33	I_{cc} Typ=275		330	mA
-	CLK2 = 80 MHz: with -40	I_{cc} Typ = 330	in a land	400	mA
Іссяв	Standby Current	I _{ccss} Typ = 0.08 mA (Notes 4, 5)		1	mA
CIN	Input or I/O Capacitance	F _c =1 MHz (Note 4)		10	pF
Cout	Output Capacitance	F _c =1 MHz (Note 4)		12	pF
CCLK	CLK2 Capacitance	F _c =1 MHz (Note 4)	and the second	20	pF

Notes: 1. The Min value, –0.3, is not 100% tested. 2. PEREQ input has an internal pulldown resistor. 3. BS16, BUSY, and ERROR inputs each have an internal pullup resistor.

4. Not 100% tested.

5. Measurement taken with BS16, BUSY, and ERROR at Vcc voltage level.

*Preliminary Information.

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SWITCHING CHARACTERISTIC over operating range

 $Vcc = 5 V \pm 5\%$; $Tcase = 0^{\circ}C$ to $+85^{\circ}C$

No.	Parameter Description	Notes	Ref Figure	40 MHz Min	40 MHz Max	Unit
	Operating Frequency	Half of CLK2 Freq	-Warga	0	40	MHz
1	CLK2 Period		3	12.5		ns
2a	CLK2 High Time	at 2 V	3	5		ns
2b	CLK2 High Time	at 3.7 V	3	3.25		ns
3a	CLK2 Low Time	at 2 V	3	5		ns
3b	CLK2 Low Time	at 0.8 V	3	3.25		ns
4	CLK2 Fall Time	3.7 V to 0.8 V (Note 3)	3		4	ns
5	CLK2 Rise Time	0.8 V to 3.7 V (Note 3)	3	1993	4	ns
6	A31-A2 Valid Delay	C _L =50 pF	2, 5, 13	4	15	ns
7	A31–A2 Float Delay	(Note 1)	13	4	20	ns
8	BE3-BE0, LOCK Valid Delay	C _L =50 pF	2, 5, 13	4	15	ns
9	BE3-BE0, LOCK Float Delay	(Note 1)	13	4	20	ns
10	W/R, M/IO, D/C Valid Delay	C _L =50 pF	2, 5, 13	4	15	ns
10a	ADS Valid Delay	C _L =50 pF	2, 5, 13	4	14.5	ns
11	W/R, M/IO, D/C, ADS Float Delay	(Note 1)	13	4	20	ns
12	D31-D0 Write Data Valid Delay	C _L =50 pF (Note 4)	2, 6, 13	7	24	ns
12a	D31-D0 Write Data Hold Time	C _L =50 pF	2,7	2		ns
13	D31-D0 Float Delay	(Note 1)	13	4	17	ns
14	HLDA Valid Delay	C _L =50 pF	2, 13	4	20	ns
15	NA Setup Time		4	5		ns
16	NA Hold Time		4	2		ns
17	BS16 Setup Time	· VERSING 1	4	5		ns
18	BS16 Hold Time		4	2		ns
19	READY Setup Time		4	7		ns
20	READY Hold Time		4	4		ns
21	D31-D0 Read Setup Time		4	5		ns
22	D31-D0 Read Hold Time		4	3		ns
23	HOLD Setup Time		4	11		ns
24	HOLD Hold Time	C STATES STATES	4	2		ns
25	RESET Setup Time	II and the late	14	5		ns
26	RESET Hold Time	Service 1	14	2		ns
27	NMI, INTR Setup Time	(Note 2)	4	5	10 11	ns
28	NMI, INTR Hold Time	(Note 2)	4	5	0	ns
29	PEREQ, ERROR, BUSY Setup Time	(Note 2)	4	5		ns
30	PEREQ, ERROR, BUSY Hold Time	(Note 2)	4	4		ns

Notes: 1. Float condition occurs when maximum output current becomes less than I_{L0} in magnitude. Float delay is not 100% tested.
 2. These inputs are allowed to be asynchronous to CLK2. The setup and hold specifications are given for testing purposes, to assure recognition within a specific clock period.
 3. Rise and fall times are not tested.
 4. Min time not 100% tested.

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SWITCHING CHARACTERISTIC over operating range Vcc = 5 V ±5%; TcASE = 0°C to +85°C

No.	Parameter Description	Notes	Ref Figures	33 MHz Min	33 MHz Max	Unit
	Operating Frequency	Half of CLK2 Freq		0	33.3	MHz
1	CLK2 Period		3	15.0		ns
2a	CLK2 High Time	at 2 V	3	6.25	19129-245	ns
2b	CLK2 High Time	at 3.7 V	3	4.5		ns
3a	CLK2 Low Time	at 2 V	3	6.25		ns
3b	CLK2 Low Time	at 0.8 V	3	4.5		ns
4	CLK2 Fall Time	3.7 V to 0.8 V (Note 3)	3		4	ns
5	CLK2 Rise Time	0.8 V to 3.7 V (Note 3)	3		4	ns
6	A31-A2 Valid Delay	C _L =50 pF	2, 5, 13	4	15	ns
7	A31-A2 Float Delay	(Note 1)	13	4	20	ns
8	BE3-BE0, LOCK Valid Delay	C _L =50 pF	2, 5, 13	4	15	ns
9	BE3-BE0, LOCK Float Delay	(Note 1)	13	4	20	ns
10	W/R, M/IO, D/C Valid Delay	C _L =50 pF	2, 5, 13	4	15	ns
10a	ADS Valid Delay	C _L =50 pF	2, 5, 13	4	14.5	ns
11	W/R, M/IO, D/C, ADS Float Delay	(Note 1)	13	4	20	ns
12	D31-D0 Write Data Valid Delay	C _L =50 pF (Note 4)	2, 6, 13	7	24	ns
12a	D31-D0 Write Data Hold Time	C _L =50 pF	2,7	2		ns
13	D31-D0 Float Delay	(Note 1)	13	4	17	ns
14	HLDA Valid Delay	C _L =50 pF	2, 13	4	20	ns
15	NA Setup Time		4	5		ns
16	NA Hold Time		4	2		ns
17	BS16 Setup Time		4	5		ns
18	BS16 Hold Time		4	2		ns
19	READY Setup Time		4	7		ns
20	READY Hold Time		4	4		ns
21	D31-D0 Read Setup Time		4	5		ns
22	D31–D0 Read Hold Time		4	3		ns
23	HOLD Setup Time		4	11		ns
24	HOLD Hold Time		4	2		ns
25	RESET Setup Time		14	5		ns
26	RESET Hold Time		14	2		ns
27	NMI, INTR Setup Time	(Note 2)	4	5		ns
28	NMI, INTR Hold Time	(Note 2)	4	5		ns
29	PEREQ, ERROR, BUSY Setup Time	(Note 2)	4	5		ns
30	PEREQ, ERROR, BUSY Hold Time	(Note 2)	4	4		ns

Notes: 1. Float condition occurs when maximum output current becomes less than I_{L0} in magnitude. Float delay is not 100% tested.
 2. These inputs are allowed to be asynchronous to CLK2. The setup and hold specifications are given for testing purposes, to assure recognition within a specific CLK2 period.
 3. Rise and fall times are not tested.
 4. Min time not 100% tested.

AMD

SWITCHING CHARACTERISTIC over operating range $V_{CC} = 5 V \pm 5$; $T_{CASE} = 0^{\circ}C$ to $+85^{\circ}C$ (PGA) $V_{CC} = 5 V \pm 10\%$; $T_{CASE} = 0^{\circ}C$ to $+100^{\circ}C$ (PQFP*)

No.	Parameter Description	Notes	Ref Figures	25 MHz Min	25 MHz Max	Unit
	Operating Frequency	Half of CLK2 Freq		0	25	MHz
1	CLK2 Period		3	20	1.	ns
2a	CLK2 High Time	at 2 V	3	7		ns
2b	CLK2 High Time	at 3.7 V	3	4		ns
3a	CLK2 Low Time	at 2 V	3	7		ns
3b	CLK2 Low Time	at 0.8 V	3	5	ST 201 SX.	ns
4	CLK2 Fall Time	3.7 V to 0.8 V (Note 3)	3		7	ns
5	CLK2 Rise Time	0.8 V to 3.7 V (Note 3)	3		7	ns
6	A31-A2 Valid Delay	C _L =50 pF	2, 5, 13	4	21	ns
7	A31–A2 Float Delay	(Note 1)	13	4	30	ns
8	BE3-BE0 Valid Delay	C _L =50 pF	2, 5, 13	4	24	ns
8a	LOCK Valid Delay	CL=50 pF	2, 5, 13	4	21	ns
9	BE3-BE0, LOCK Float Delay	(Note 1)	13	4	30	ns
10	W/R, M/IO, D/C, ADS Valid Delay	C _L =50 pF	2, 5, 13	4	21	ns
11	W/R, M/IO, D/C, ADS Float Delay	(Note 1)	13	4	30	ns
12	D31-D0 Write Data Valid Delay	C _L =50 pF	2, 6, 13	7	27	ns
12a	D31-D0 Write Data Hold Time	C _L =50 pF	2,7	2		ns
13	D31-D0 Float Delay	(Note 1)	13	4	22	ns
14	HLDA Valid Delay	C _L =50 pF	2,13	4	22	ns
15	NA Setup Time		4	7		ns
16	NA Hold Time		4	3		ns
17	BS16 Setup Time		4	7	U.S. C. LOANS	ns
18	BS16 Hold Time		4	3	18. 19.15	ns
19	READY Setup Time		4	9		ns
20	READY Hold Time		4	4		ns
21	D31-D0 Read Setup Time		4	7		ns
22	D31-D0 Read Hold Time		4	5		ns
23	HOLD Setup Time		4	15		ns
24	HOLD Hold Time		4	3		ns
25	RESET Setup Time	1.1 1.1 1. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1.	14	10		ns
26	RESET Hold Time	A CONTRACTOR	14	3		ns
27	NMI, INTR Setup Time	(Note 2)	4	6	C. A. M.	ns
28	NMI, INTR Hold Time	(Note 2)	4	6		ns
29	PEREQ, ERROR, BUSY Setup Time	(Note 2)	4	6		ns
30	PEREQ, ERROR, BUSY Hold Time	(Note 2)	4	5		ns

Notes: 1. Float condition occurs when maximum output current becomes less than I_{Lo} magnitude. Float delay is not 100% tested.
2. These inputs are allowed to be asynchronous to CLK2. The setup and hold specifications are given for testing purposes, to assure recognition within a specific CLK2 period.
3. Rise and fall times are not tested.

*Preliminary Information.

AMD C

SWITCHING CHARACTERISTIC over operating range $Vcc = 5 V \pm 5\%$; $TcASE = 0^{\circ}C$ to $+85^{\circ}C$ (PGA) $Vcc = 5 V \pm 10\%$; $TcASE = 0^{\circ}C$ to $+100^{\circ}C$ (PQFP*)

No.	Parameter Description	Notes	Ref Figures	20 MHz Min	20 MHz Max	Unit
	Operating Frequency	Half of CLK2 Freq		0	20	MHz
1	CLK2 Period	anistikis - nazile	3	25		ns
2a	CLK2 High Time	at 2 V	3	8	12.25 674-46	ns
2b	CLK2 High Time	at (Vcc-0.8 V)	3	5	Carlo Antes	ns
3a	CLK2 Low Time	at 2 V	3	8		ns
3b	CLK2 Low Time	at 0.8 V	3	6		ns
4	CLK2 Fall Time	(V _{cc} -0.8 V) to 0.8 V (Note 3)	3		8	ns
5	CLK2.Rise Time	0.8 V to (V _{cc} -0.8 V) (Note 3)	3	. Sures	8	ns
6	A31–A2 Valid Delay	C _L = 120 pF	2, 5, 13	4	30	ns
7	A31–A2 Float Delay	(Note 1)	13	4	32	ns
8	BE3-BE0 Valid Delay	C _L =75 pF	2, 5, 13	4	30	ns
9	BE3–BE0, LOCK Float Delay	(Note 1)	13	4	32	ns
10	W/R, M/IO, D/C, ADS Valid Delay	С _L = 75 pF	2, 5, 13	4	28	ns
11	W/R, M/IO, D/C, ADS Float Delay	(Note 1)	13	4	30	ns
12	D31-D0 Write Data Valid Delay	C _L =120 pF	2, 8, 13	4	38	ns
13	D31-D0 Float Delay	(Note 1)	13	4	27	ns
14	HLDA Valid Delay	C _L =75 pF	2, 13	6	28	ns
15	NA Setup Time	Once a la	4	9	1.0.100	ns
16	NA Hold Time		4	14		ns
17	BS16 Setup Time		4	13		ns
18	BS16 Hold Time		4	21		ns
19	READY Setup Time	- Contraction	4	12		ns
20	READY Hold Time		4	4	C. S. Martine	ns
21	D31-D0 Read Setup Time		4	11		ns
22	D31-D0 Read Hold Time		4	6	and the second second	ns
23	HOLD Setup Time		4	17		ns
24	HOLD Hold Time		4	5		ns
25	RESET Setup Time		14	12		ns
26	RESET Hold Time		14	4	- California	ns
27	NMI, INTR Setup Time	(Note 2)	4	16	1.111 19 19	ns
28	NMI, INTR Hold Time	(Note 2)	4	16	- 10. 100	ns
29	PEREQ, ERROR, BUSY Setup Time	(Note 2)	4	14		ns
30	PEREQ, ERROR, BUSY Hold Time	(Note 2)	4	5		ns

Notes: 1. Float condition occurs when maximum output current becomes less than I_{LO} magnitude. Float delay is not 100% tested.
2. These inputs are allowed to be asynchronous to CLK2. The setup and hold specifications are given for testing purposes, to assure recognition within a specific CLK2 period.
3. Rise and fall times are not tested.
*Preliminary Information.

AMD

SWITCHING WAVEFORMS

The switching characteristics consist of output delays, input setup requirements, and input hold requirements. All characteristics are relative to the CLK2 rising edge crossing the 2.0 V level.

Switching characteristic measurement is defined by Figure 1. Inputs must be driven to the voltage levels indicated by this diagram. Am386DXL microprocessor output delays are specified with minimum and maximum limits, measured as shown. The minimum Am386DXL microprocessor delay times are hold times provided to external circuitry. Am386DXL microprocessor input setup and hold times are specified as minimums, defining the smallest acceptable sampling window. Within the sampling window, a synchronous input signal must be stable for correct Am386DXL microprocessor operation.

Outputs NA, W/R, D/C, M/IO, LOCK, BE3–BE0, A31–A2, and HLDA only change at the beginning of phase one. D31–D0 (write cycles) only change at the beginning of phase two. The READY, HOLD, BUSY, ERROR, PEREQ, and D31–D0 (read cycles) inputs are sampled at the beginning of phase one. The NA, BS16, INTR, and NMI inputs are sampled at the beginning of phase two.

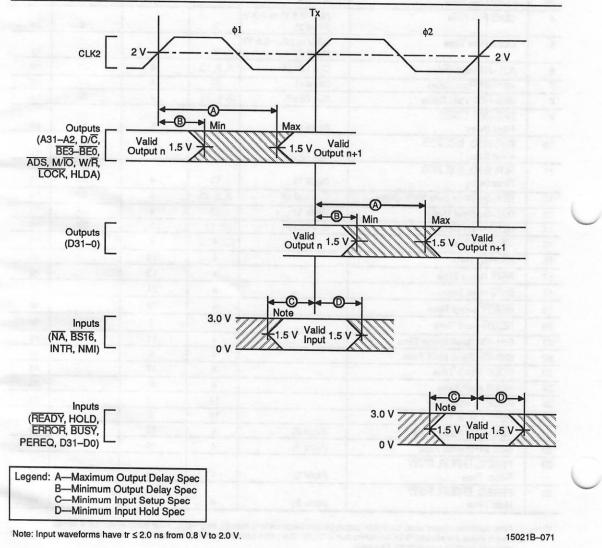


Figure 1. Drive Levels and Measurement Points

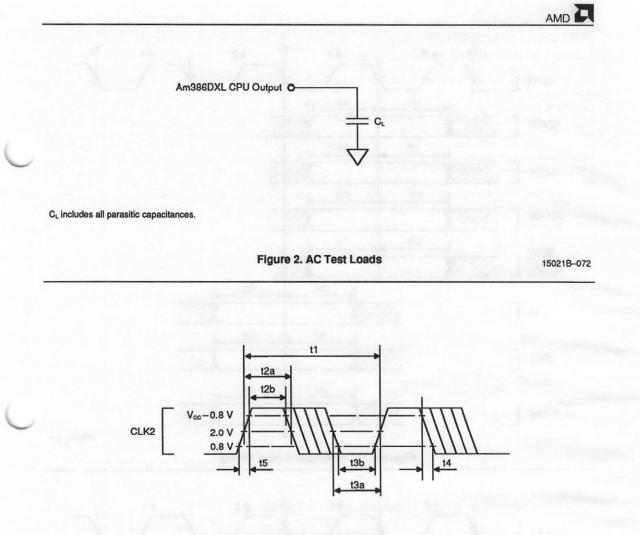
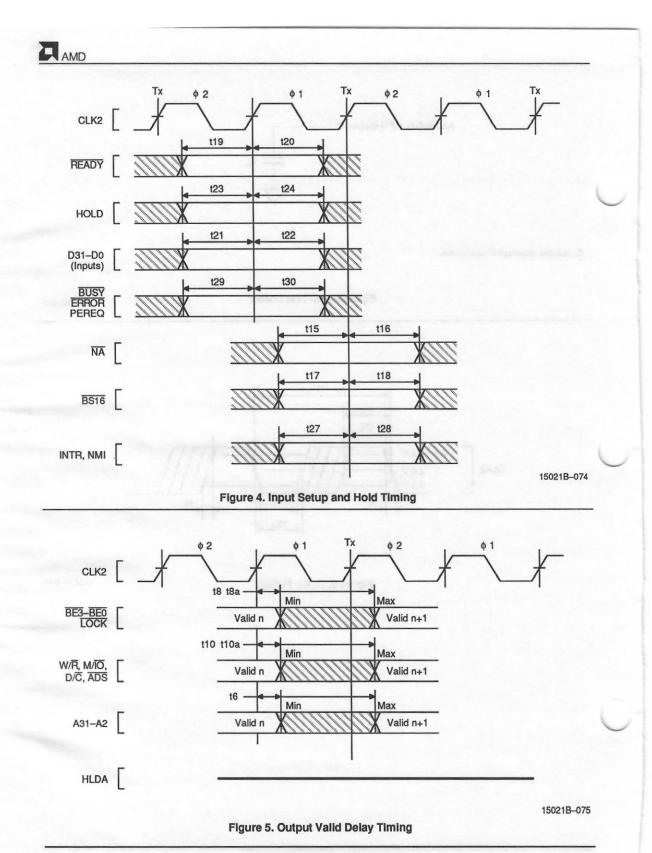


Figure 3. CLK2 Timing

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Am386DXL Microprocessor

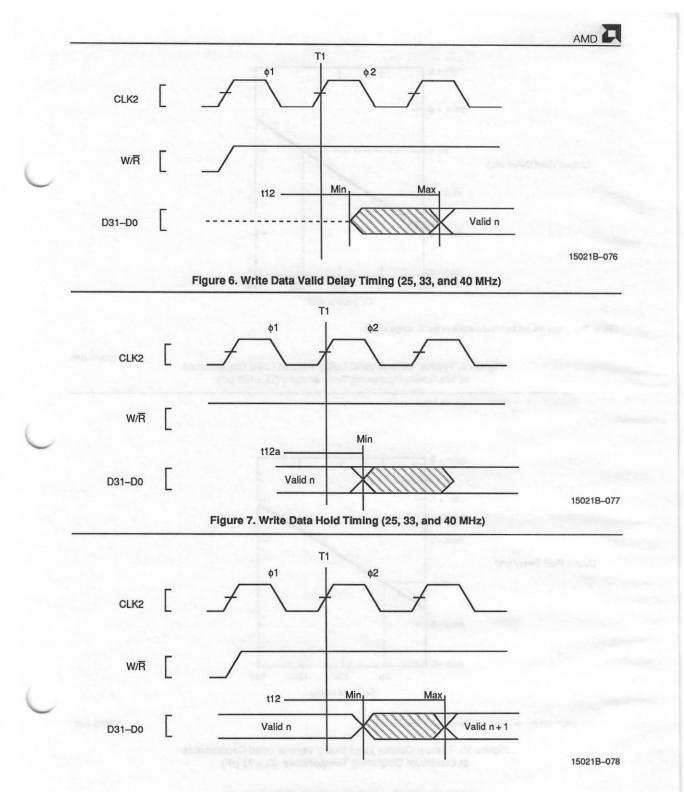
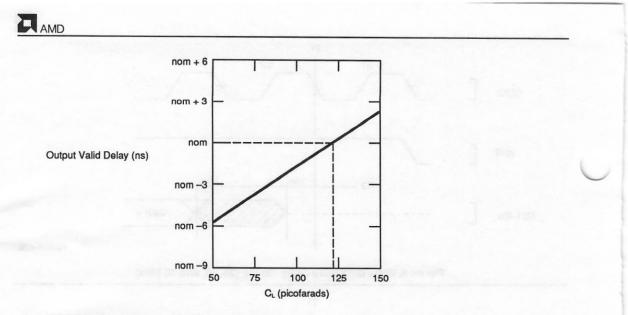
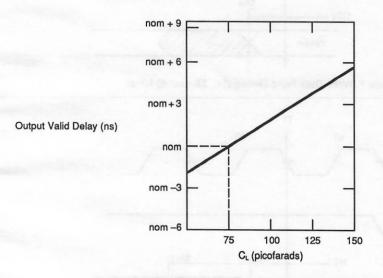


Figure 8. Write Data Valid Delay Timing (20 MHz)



Note: This graph will not be linear outside of the \mathbf{C}_{L} range shown.

Figure 9. Typical Output Valid Delay Versus Load Capacitance at Maximum Operating Temperature (CL=120 pF)

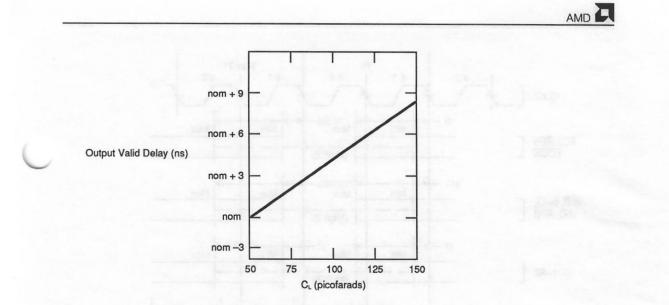


Note: This graph will not be linear outside of the CL range shown.

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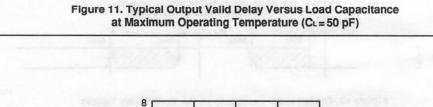
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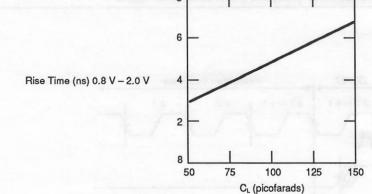
Figure 10. Typical Output Valid Delay Versus Load Capacitance at Maximum Operating Temperature (CL=75 pF)



Note: This graph will not be linear outside of the CL range shown.

15021B-081

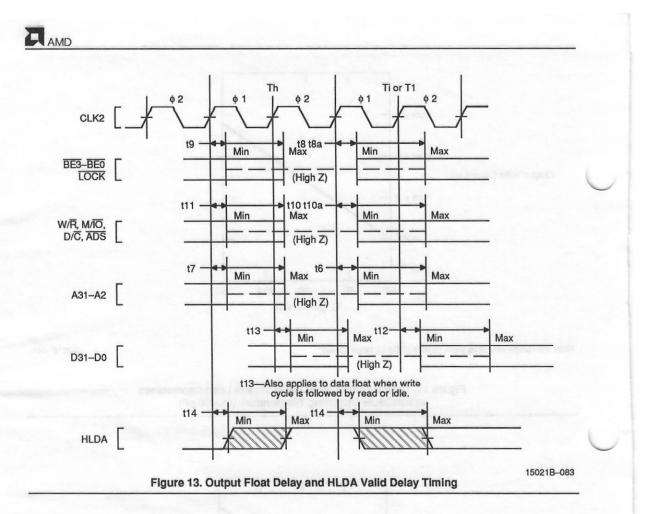


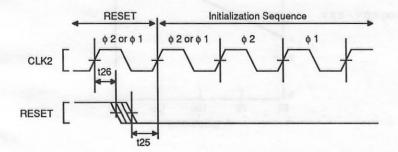


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Note: This graph will not be linear outside of the C_L range shown.

Figure 12. Typical Output Rise Time Versus Load Capacitance at Maximum Operating Temperature



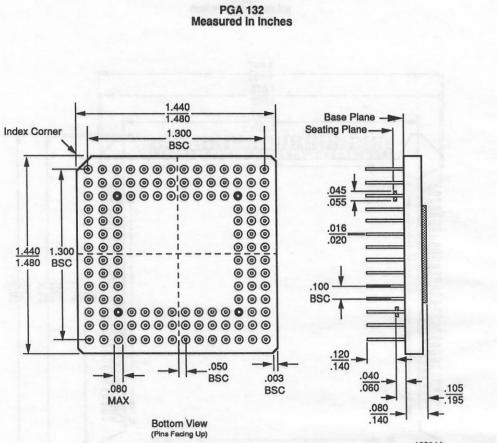


The second internal processor phase following RESET High-to-Low transition (provided t25 and t26 are met) is \$2.

Figure 14. RESET Setup and Hold Timing and Internal Phase

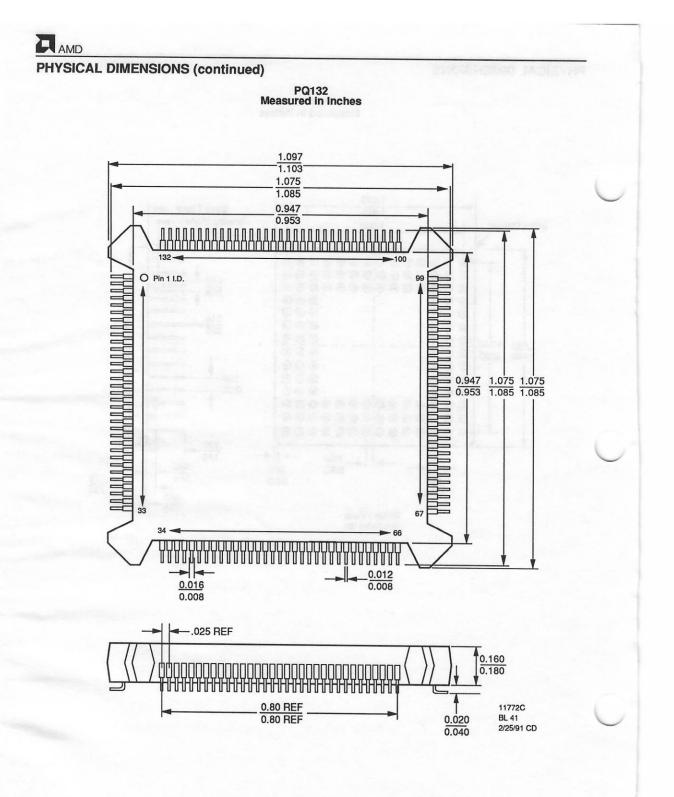
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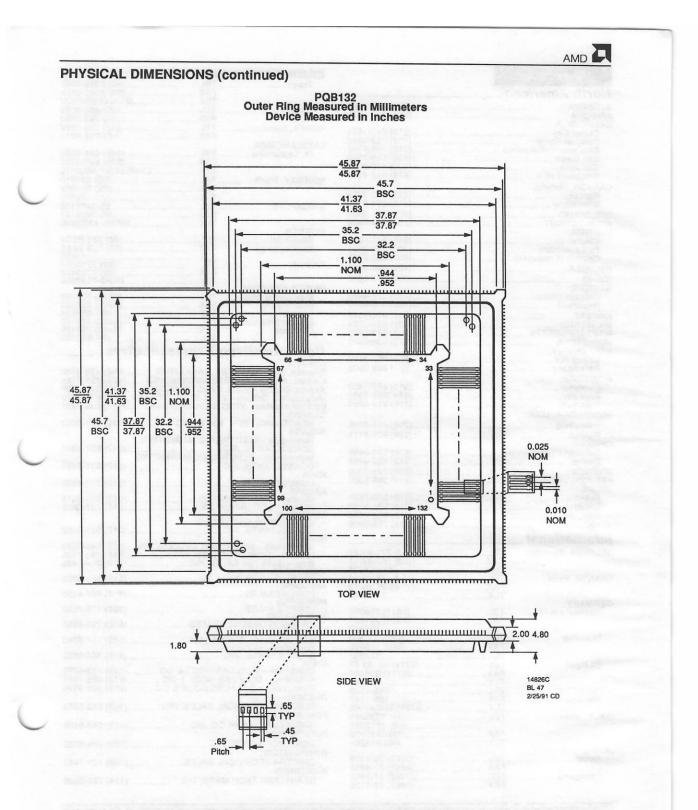




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